

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST

CONVEYING PARTY DATA

Name	Execution Date
SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC	08/03/2022
ON SEMICONDUCTOR CONNECTIVITY SOLUTIONS, INC.	08/03/2022

RECEIVING PARTY DATA

Name:	DEUTSCHE BANK AG NEW YORK BRANCH, AS COLLATERAL AGENT
Street Address:	60 WALL STREET
City:	NEW YORK
State/Country:	NEW YORK
Postal Code:	10005

PROPERTY NUMBERS Total: 76

Property Type	Number
Application Number:	17657655
Application Number:	17657768
Application Number:	17657783
Application Number:	17658006
Application Number:	17658071
Application Number:	17658118
Application Number:	17658153
Application Number:	17658232
Application Number:	17658387
Application Number:	17658771
Application Number:	17658881
Application Number:	17658885
Application Number:	17659068
Application Number:	17659250
Application Number:	17659290
Application Number:	17659363
Application Number:	17659388
Application Number:	17659885
Application Number:	17659901

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Property Type	Number
Application Number:	17659993
Application Number:	17660076
Application Number:	17660319
Application Number:	17660477
Application Number:	17660678
Application Number:	17660691
Application Number:	17660860
Application Number:	17660941
Application Number:	17661094
Application Number:	17661420
Application Number:	17661890
Application Number:	17662263
Application Number:	17662786
Application Number:	17663331
Application Number:	17663336
Application Number:	17663483
Application Number:	17663863
Application Number:	17664133
Application Number:	17664138
Application Number:	17664273
Application Number:	17664277
Application Number:	17664482
Application Number:	17664485
Application Number:	17664549
Application Number:	17664749
Application Number:	17664839
Application Number:	17739672
Application Number:	17739908
Application Number:	17739954
Application Number:	17744979
Application Number:	17804404
Application Number:	17804423
Application Number:	17804460
Application Number:	17804692
Application Number:	17804709
Application Number:	17804944
Application Number:	17805131
Application Number:	17805824

Property Type	Number
Application Number:	17805916
Application Number:	17806144
Application Number:	17806308
Application Number:	17806597
Application Number:	17806817
Application Number:	17806961
Application Number:	17807170
Application Number:	17807281
Application Number:	17807749
Application Number:	17808338
Application Number:	17808716
Application Number:	17854663
Application Number:	17855118
Application Number:	63362418
Application Number:	63362638
Application Number:	63363696
Application Number:	63364166
Application Number:	63364400
Application Number:	63366198

CORRESPONDENCE DATA

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.
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Correspondent Name: SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
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Address Line 4: PHOENIX, ARIZONA 85008

ATTORNEY DOCKET NUMBER:	Q2 2022 PSA
NAME OF SUBMITTER:	KELLY A. HALL
SIGNATURE:	/Kelly A. Hall/
DATE SIGNED:	08/04/2022

Total Attachments: 9
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PATENT SECURITY AGREEMENT

This PATENT SECURITY AGREEMENT, dated as of August 3, 2022 ("Patent Security Agreement"), made by each of the signatories hereto (together with any other entity that may become a party hereto as provided herein, the "Patent Grantors"), is in favor of DEUTSCHE BANK AG NEW YORK BRANCH, as collateral agent (in such capacity, the "Collateral Agent") for the Secured Parties.

WITNESSETH:

WHEREAS, the Patent Grantors are party to a Guarantee and Collateral Agreement dated as of April 15, 2016 (the "Guarantee and Collateral Agreement") in favor of the Collateral Agent pursuant to which the Patent Grantors are required to execute and deliver this Patent Security Agreement (capitalized terms used but not otherwise defined herein shall have the meanings given to them in the Guarantee and Collateral Agreement);

WHEREAS, pursuant to the terms of the Guarantee and Collateral Agreement, each Patent Grantor has created in favor of the Collateral Agent a security interest in, and the Collateral Agent has become a secured creditor with respect to, the Patent Collateral (as defined below);

NOW, THEREFORE, in consideration of the premises and to induce the Agents and the Lenders to enter into the Credit Agreement and to induce Lenders to make their respective extensions of credit to the Borrower thereunder and to induce the Qualified Counterparties to enter into the Specified Hedge Agreements and the Specified Cash Management Agreements and provide financial accommodation, each Patent Grantor hereby grants to the Collateral Agent, for the benefit of the Secured Parties, a security interest in all of the following property now owned or at any time hereafter acquired by such Patent Grantor or in which such Patent Grantor now has or at any time in the future may acquire any right, title or interest (collectively, the "Patent Collateral"), as collateral security for the complete payment and performance when due (whether at the stated maturity, by acceleration or otherwise) of all Secured Obligations:

(a) all Patents of such Patent Grantor, including, without limitation, the registered and applied-for Patents of such Grantor listed on Schedule 1 attached hereto;

(b) to the extent not covered by clause (a), all Proceeds of any of the foregoing;
and

(c) to the extent not covered by clause (a), all causes of action arising prior to or after the date hereof for infringement of any of the Patents;

provided, that (i) this Patent Security Agreement shall not constitute a grant of a security interest in any property to the extent that and for as long as such grant of a security interest would be prohibited by the terms of the Guarantee and Collateral Agreement; and (ii) the security interest granted hereby (x) shall attach at all times to all proceeds of such property, (y) shall attach to such property immediately and automatically (without need for any further grant or act) at such time as the condition described in clause (i) ceases to exist and (z) to the extent severable shall in any event

attach to all rights in respect of such property that are not subject to the applicable condition described in clause (i).

The security interest granted pursuant to this Patent Security Agreement is granted in conjunction with security interest granted to the Collateral Agent pursuant to the Guarantee and Collateral Agreement and the Patent Grantors hereby acknowledge and affirm that the rights and remedies of the Collateral Agent with respect to the security interest in the Patents made and granted hereby are more fully set forth in the Guarantee and Collateral Agreement. In the event that any provision of this Patent Security Agreement is deemed to conflict with the Guarantee and Collateral Agreement, the provisions of the Guarantee and Collateral Agreement shall govern.

Each Patent Grantor hereby authorizes and requests that the Commissioner of Patents and Trademarks record this Patent Security Agreement.

THIS PATENT SECURITY AGREEMENT AND THE RIGHTS AND OBLIGATIONS OF THE PARTIES UNDER THIS PATENT SECURITY AGREEMENT SHALL BE GOVERNED BY, AND CONSTRUED AND INTERPRETED IN ACCORDANCE WITH, THE LAW OF THE STATE OF NEW YORK.

This Patent Security Agreement may be executed by one or more of the parties to this Patent Security Agreement on any number of separate counterparts, and all of said counterparts taken together shall be deemed to constitute one and the same instrument. Delivery of an executed signature page of this Patent Security Agreement by facsimile transmission or electronic transmission (in PDF format) shall be effective as delivery of a manually executed counterpart hereof. A copy of this Patent Security Agreement signed by all the parties shall be delivered to the Administrative Agent.

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IN WITNESS WHEREOF, each Grantor has caused this PATENT SECURITY AGREEMENT to be executed and delivered by its duly authorized officer as of the date first above written.

SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC

By: 

Name: Bernard Colpitts

Title: Chief Accounting Officer, SVP of Finance and Treasury

ON SEMICONDUCTOR CONNECTIVITY SOLUTIONS, INC.

By: 

Name: Bernard Colpitts

Title: Chief Accounting Officer, SVP of Finance and Treasury

PATENTS

Patent Applications

	Status	App Title	App No.	Filing Date	Patent No.	Grant Date	Owner
1	Application	CROSSOVER POINT CORRECTION OF DIFFERENTIAL SIGNAL	17/657655	4/1/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
2	Application	A ROTOR FOR INDUCTIVE SLIP, ECCENTRICITY, AND TILT SENSING	17/657768	4/4/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
3	Application	HARMONIC DISTORTION REDUCTION IN INDUCTIVE POSITION SENSORS	17/657783	4/4/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
4	Application	BATTERY HAZARD DETECTION	17/658006	4/5/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
5	Published	MULTI-FACED MOLDED SEMICONDUCTOR PACKAGE AND RELATED METHODS	17/658071	4/5/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
6	Application	THERMAL PERFORMANCE IMPROVEMENT AND STRESS REDUCTION IN SEMICONDUCTOR DEVICE MODULES	17/658118	4/6/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
7	Application	OPTICAL SYSTEMS WITH TILTABLE FILTERS	17/658153	4/6/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
8	Application	OXIDATION AND CORROSION PREVENTION IN SEMICONDUCTOR DEVICES AND SEMICONDUCTOR DEVICE ASSEMBLIES	17/658232	4/6/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
9	Application	HYBRID INDUCTOR CURRENT MONITORING FOR POWER SWITCH	17/658387	4/7/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
10	Application	BACKSIDE OHMIC CONTACTS FOR SEMICONDUCTOR DEVICES	17/658771	4/11/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
11	Application	CLIP DESIGN AND METHOD OF CONTROLLING CLIP POSITION	17/658881	4/12/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
12	Application	FLEXIBLE CLIP	17/658885	4/12/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC

	Status	App Title	App No.	Filing Date	Patent No.	Grant Date	Owner
13	Published	BACKMETAL REMOVAL METHODS	17/659068	4/13/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
14	Application	OUTPUT OVERVOLTAGE PROTECTION FOR A TOTEM POLE POWER FACTOR CORRECTION CIRCUIT	17/659250	4/14/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
15	Application	IMAGE SENSORS HAVING DIELECTRIC RELAXATION CORRECTION CIRCUITRY	17/659290	4/14/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
16	Application	THERMAL MISMATCH REDUCTION IN SEMICONDUCTOR DEVICE MODULES	17/659363	4/15/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
17	Published	SINGULATION OF SILICON CARBIDE SEMICONDUCTOR WAFERS	17/659388	4/15/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
18	Application	SEMICONDUCTOR PACKAGE AND RELATED METHODS	17/659885	4/20/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
19	Application	IMAGE SENSOR PACKAGE	17/659901	4/20/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
20	Application	SEMICONDUCTOR DEVICES AND METHODS OF MANUFACTURING SEMICONDUCTOR DEVICES	17/659993	4/20/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
21	Application	SEMICONDUCTOR DEVICE INCLUDING BONDING COVERS	17/660076	4/21/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
22	Application	SEMICONDUCTOR PACKAGE SYSTEM AND RELATED METHODS	17/660319	4/22/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
23	Application	SEMICONDUCTOR PACKAGES WITH DIE INCLUDING CAVITIES AND RELATED METHODS	17/660477	4/25/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
24	Application	HIGH DYNAMIC RANGE IMAGING PIXELS WITH MULTIPLE PHOTODIODES	17/660678	4/26/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
25	Application	ELECTRONIC DEVICE INCLUDING A TRANSISTOR AND A SHIELD ELECTRODE	17/660691	4/26/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
26	Application	EXPANDED IMAGE SENSOR PIXEL ARRAY	17/660860	4/27/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC

	Status	App Title	App No.	Filing Date	Patent No.	Grant Date	Owner
27	Application	REINFORCED SEMICONDUCTOR DIE AND RELATED METHODS	17/660941	4/27/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
28	Application	METHOD AND SYSTEM OF A POWER CONVERTER WITH SECONDARY SIDE ACTIVE CLAMP	17/661094	4/28/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
29	Application	MULTI-CHIP SYSTEM-IN-PACKAGE	17/661420	4/29/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
30	Application	SEMICONDUCTOR DEVICE AND METHOD FOR SUPPORTING ULTRA-THIN SEMICONDUCTOR DIE	17/661890	5/3/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
31	Application	SEMICONDUCTOR DEVICES AND METHODS OF MANUFACTURING SEMICONDUCTOR DEVICES	17/662263	5/6/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
32	Application	SEMICONDUCTOR PACKAGE ELECTRICAL CONTACTS AND RELATED METHODS	17/662786	5/10/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
33	Application	CONFIGURABLE LOW OHMIC POWER CIRCUITS	17/663331	5/13/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
34	Application	IMAGE SENSORS WITH HYBRID ANALOG-TO-DIGITAL CONVERTER ARCHITECTURE	17/663336	5/13/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
35	Application	LOW-NOISE AMPLIFIER (LNA) WITH HIGH POWER SUPPLY REJECTION RATIO (PSRR)	17/663483	5/16/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
36	Application	PROCESS OF FORMING AN ELECTRONIC DEVICE INCLUDING A POLYMER SUPPORT LAYER	17/663863	5/18/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
37	Application	IMAGE SENSOR PACKAGING STRUCTURES AND RELATED METHODS	17/664133	5/19/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
38	Application	IMAGE SENSOR PACKAGING STRUCTURES AND RELATED METHODS	17/664138	5/19/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
39	Application	FLEXIBLE DISTRIBUTED ANTENNA ARRAY	17/664273	5/20/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
40	Application	CROSSOVER POINT CORRECTION OF DIFFERENTIAL SIGNAL	17/657655	4/1/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC

	Status	App Title	App No.	Filing Date	Patent No.	Grant Date	Owner
41	Application	DRIVER FOR MITIGATING HIGH-VOLTAGE SURGES AT HOST AND SINK INTERFACE DEVICES	17/664277	5/20/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
42	Application	IMMERSION COOLING PACKAGE	17/664482	5/23/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
43	Application	OPTOELECTRONIC DEVICE HAVING A MODULAR PACKAGE	17/664485	5/23/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
44	Application	IMMERSION DIRECT COOLING MODULES AND RELATED METHODS	17/664549	5/23/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
45	Application	SUBMODULE SEMICONDUCTOR PACKAGE	17/664749	5/24/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
46	Application	DRIVE METHODS FOR A THREE-PHASE MOTOR	17/664839	5/24/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
47	Application	STEERING MATRIX DERIVATION	17/739672	5/9/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
48	Application	ERROR CORRECTION OVERWRITE FOR AUDIO ARTIFACT REDUCTION	17/739908	5/9/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
49	Application	TRANSMISSION ERROR ROBUST ADPCM COMPRESSOR WITH ENHANCED RESPONSE	17/739954	5/9/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
50	Application	EARLY LINK DETECTION BASED ADAPTIVE SELECTION OF RECEIVE PARAMETERS	17/744979	5/16/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
51	Application	SYSTEM AND METHODS FOR SWITCHING AN ACTIVE CLAMP FLYBACK CONVERTER	17/804404	5/27/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
52	Application	POWER MODULES AND RELATED METHODS	17/804423	5/27/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
53	Application	EPITAXIAL FIELD STOP REGION FOR SEMICONDUCTOR DEVICES	17/804460	5/27/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
54	Application	INTERFERENCE FILTER AND ELECTROSTATIC DISCHARGE / ELECTRICAL SURGE PROTECTION CIRCUIT AND DEVICE	17/804692	5/31/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
55	Application	MULTIPHASE TRANS-INDUCTOR VOLTAGE	17/804709	5/31/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC

	Status	App Title	App No.	Filing Date	Patent No.	Grant Date	Owner
		REGULATOR FAULT DIAGNOSTIC					
56	Application	OFFSET CANCEL SYSTEMS AND METHODS FOR RESOLVER-TYPE SENSORS	17/804944	6/1/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
57	Application	STRUCTURES AND METHODS FOR SOURCE-DOWN VERTICAL SEMICONDUCTOR DEVICE	17/805131	6/2/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
58	Application	DIODES INCLUDING MULTIPLE SCHOTTKY CONTACTS	17/805824	6/7/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
59	Application	WIDE VOLTAGE RANGE INPUT AND OUTPUT CIRCUITS	17/805916	6/8/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
60	Application	SILICON-ON-INSULATOR DIE SUPPORT STRUCTURES AND RELATED METHODS	17/806144	6/9/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
61	Application	LOW POWER OSCILLATOR WITH VARIABLE DUTY CYCLE AND METHOD THEREFOR	17/806308	6/10/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
62	Application	INTEGRATED TRANSISTOR AND RESISTOR-DIODE-CAPACITOR SNUBBER	17/806597	6/13/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
63	Application	FAULT PROTECTION TESTING IN A HIGH-POWER SWITCHING SYSTEM	17/806817	6/14/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
64	Application	DUAL SIDE DIRECT COOLING SEMICONDUCTOR PACKAGE	17/806961	6/15/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
65	Application	WIDE INPUT VOLTAGE RANGE LOW-POWER CHARGE PUMP BASED LDO	17/807170	6/16/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
66	Application	BEAMFORMER SOLICITED SOUNDING	17/807281	6/16/2022	N/A	N/A	ON Semiconductor Connectivity Solutions, Inc.
67	Application	POWER MODULE	17/807749	6/20/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
68	Application	SEMICONDUCTOR PACKAGE ELECTRICAL CONTACT STRUCTURES AND RELATED METHODS	17/808338	6/23/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC

	Status	App Title	App No.	Filing Date	Patent No.	Grant Date	Owner
69	Application	SUBSTRATE ALIGNMENT SYSTEMS AND RELATED METHODS	17/808716	6/24/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
70	Application	GATE DRIVER WITH TEMPERATURE MONITORING FEATURES	17/854663	6/30/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
71	Application	MULTICHANNEL MINIMUM DISTANCE CHIRP ECHO DETECTION	17/855118	6/30/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
72	Application	SHIELDED GATE ACCUMULATION FET WITH A T-SHAPED MESA	63/362418	4/4/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
73	Application	TRANSFER MOLDED POWER MODULE	63/362638	4/7/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
74	Application	ACTIVE GATE DRIVER FOR JUNCTION TEMPERATURE BALANCING IN PARALLEL OPERATION OF BIPOLAR TRANSISTORS	63/363696	4/27/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
75	Application	POWER MODULE	63/364166	5/4/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
76	Application	INTEGRATED RTC SNUBBER TO REDUCE OVERVOLTAGE IN SMART POWER STAGES	63/366198	6/10/2022	N/A	N/A	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC